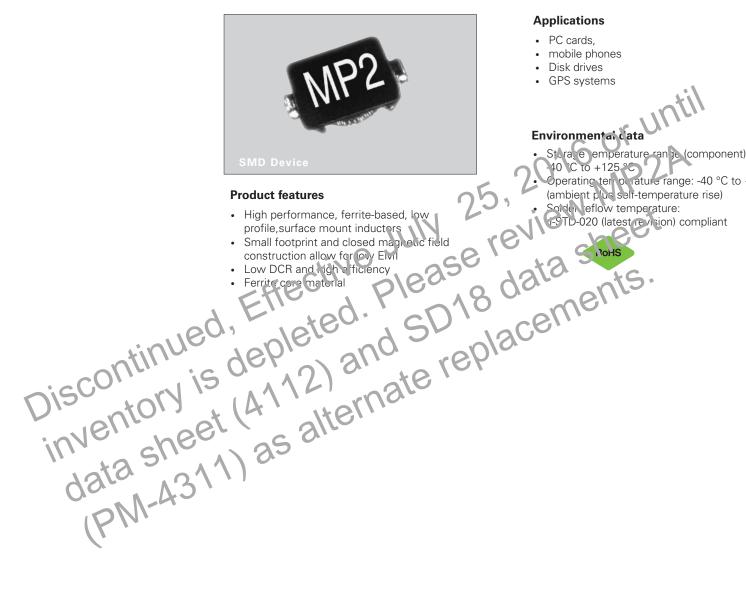
MP2 MICRO-PAC™ Low profile toroid power inductors



Applications

- · PC cards,

- St. ra; e remperature ran je (component):
- -40 °C to +125 °C Operating terrograture range: -40 °C to +125 °C





Powering Business Worldwide

Product specifications

Part Number	Inductance µH	OCL (1) μH ± 20%	Irms (2) Amperes (Typ.)	Isat (3) Amperes (Typ.)	DCR (4) Ohms (Max.)	Q (5) (Typ.)	SRF MHz (Typ.)
MP2-R47-R	0.47	0.40	2.02	3.40	0.075	10	300
MP2-1R0-R	1.0	1.02	1.67	2.10	0.103	20	160
MP2-1R5-R	1.5	1.59	1.51	1.70	0.118	25	155
MP2-2R2-R	2.2	2.29	1.39	1.40	0.130	32	150
MP2-3R3-R	3.3	3.58	1.25	1.10	0.156	42	140
MP2-4R7-R	4.7	4.60	1.18	1.00	0.180	46	130
MP2-6R8-R	6.8	7.02	1.06	0.80	0.202	46	110
MP2-100-R	10.0	9.95	0.98	0.68	0.240	55	100
MP2-150-R	15.0	15.30	0.88	0.54	0.300	65	60
MP2-220-R	22.0	21.80	0.80	0.45	0.360	65	45
MP2-330-R	33.0	33.70	0.64	0.37	0.556	65	35
MP2-470-R	47.0	46.40	0.52	0.31	0.833	65	39

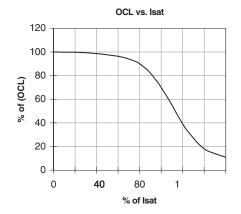
- 1) Open Circuit Inductance Test Parameters: 100kHz, 0.250 Vrms, 0.0 Adc 2) RMS current, delta temp. of 40° C ambient temperature of 85° C 3) Peak current for approximately 30% roll-off

- 4) Values @ 20° C 5) Measured @ 300KHz

Dimensions- mm



Inductance characteristics



Solder Reflow Profile

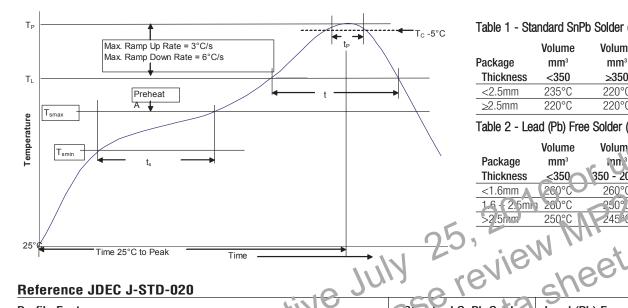


Table 1 - Standard SnPb Solder (T_c)

	Volume	Volume
Package	mm³	mm^3
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package	Volume mm³	Volume Inn ³	∕o!ume mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5n.m	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. 1 Smin	1000	150°C
• Temperature max. (I smax)	150°C	200°C
• Time (Temin to Temax) (te	60-120 Second's	60-120 Seconds
Average ramp up rate T _{Srnav} to T _p	3°C/ Second Max.	3°C/ Second Max.
Liquidous tempo rature (rc)	183°C	217°C
Time at liquillous (t _L)	60-150 Seconds	60-150 Seconds
Peak paskage body temperal lie (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(t_p)^{**}$	20 Seconds**	30 Seconds**
Average is n p-down rate (Tp to 1 max)	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak 1\mp arature	6 Minutes Max.	8 Minutes Max.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Compan . Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant inju y to the user.

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Eaton Electronics Division

1000 Eaton Boulevard Cleveland, OH 44122 United States www.eaton.com/electronics

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^{*}Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.